



## Material Content Data Sheet



<b>Sales Product Name</b>				IPL65R230C7		<b>Issued</b>		22. January 2018	
<b>MA#</b>				MA001244948					
<b>Package</b>				PG-VSON-4-1		<b>Weight*</b>		187.65 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.621	1.93	1.93	19295	19295	
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		68		
	non noble metal	zinc	7440-66-6	0.051	0.03		271		
	non noble metal	iron	7439-89-6	1.017	0.54		5420		
wire	non noble metal	copper	7440-50-8	41.300	22.01	22.59	220094	225853	
	non noble metal	copper	7440-50-8	0.898	0.48	0.48	4783	4783	
	encapsulation	organic material	carbon black	1333-86-4	0.220	0.12		1170	
plastics	plastics	epoxy resin	-	11.308	6.03		60264		
	inorganic material	silicondioxide	60676-86-0	98.262	52.36	58.51	523648	585082	
	leadfinish	non noble metal	tin	7440-31-5	2.397	1.28	1.28	12776	12776
plating	noble metal	silver	7440-22-4	0.252	0.13	0.13	1343	1343	
solder	noble metal	silver	7440-22-4	0.081	0.04		433		
	non noble metal	tin	7440-31-5	0.065	0.03		347		
	non noble metal	lead	7439-92-1	3.107	1.66	1.73	16558	17338	
heatspreader	inorganic material	phosphorus	7723-14-0	0.008	0.00		40		
	non noble metal	zinc	7440-66-6	0.030	0.02		160		
	non noble metal	iron	7439-89-6	0.601	0.32		3205		
	non noble metal	copper	7440-50-8	24.418	13.01	13.35	130125	133530	
*deviation	< 10%			Sum in total:		100.00		1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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